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Applications of "**Embedded - Microcontrollers**"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4321-i-ml

PIC18F2XXX/4XXX FAMILY

TABLE 2-1: **PIN DESCRIPTIONS (DURING PROGRAMMING): PIC18F2XXX/4XXX FAMILY**

| Pin Name | During Programming | | |
	Pin Name	Pin Type	Pin Description
$\overline{MCLR}$/VPP/RE3	VPP	P	Programming Enable
VDD[(2)]	VDD	P	Power Supply
VSS[(2)]	VSS	P	Ground
RB5	PGM	I	Low-Voltage ICSP™ Input when LVP Configuration bit equals '1'[(1)]
RB6	PGC	I	Serial Clock
RB7	PGD	I/O	Serial Data

Legend: I = Input, O = Output, P = Power
Note 1: See Figure 5-1 for more information.
2: All power supply (VDD) and ground (VSS) pins must be connected.

The following devices are included in 28-pin SPDIP, PDIP and SOIC parts:

- PIC18F2221
- PIC18F2321
- PIC18F2410
- PIC18F2420
- PIC18F2423
- PIC18F2450
- PIC18F2455
- PIC18F2458

- PIC18F2480
- PIC18F2510
- PIC18F2515
- PIC18F2520
- PIC18F2523
- PIC18F2525
- PIC18F2550
- PIC18F2553

- PIC18F2580
- PIC18F2585
- PIC18F2610
- PIC18F2620
- PIC18F2680
- PIC18F2682
- PIC18F2685

The following devices are included in 28-pin SSOP parts:

- PIC18F2221
- PIC18F2321

FIGURE 2-1: **28-Pin SPDIP, PDIP, SOIC,SSOP**

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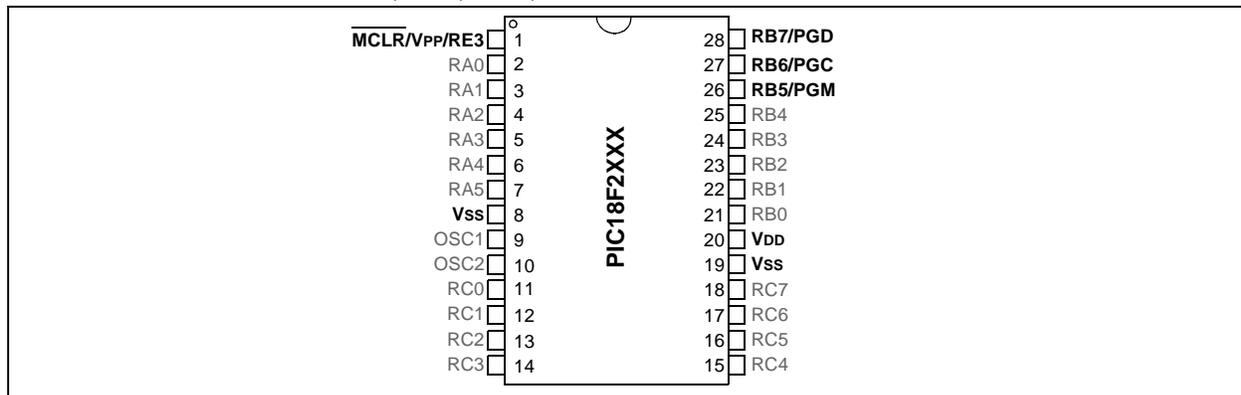
The following devices are included in 28-pin QFN parts:

- PIC18F2221
- PIC18F2321
- PIC18F2410
- PIC18F2420

- PIC18F2423
- PIC18F2450
- PIC18F2480

- PIC18F2510
- PIC18F2520
- PIC18F2523

- PIC18F2580
- PIC18F2682
- PIC18F2685

FIGURE 2-2:   28-Pin QFN
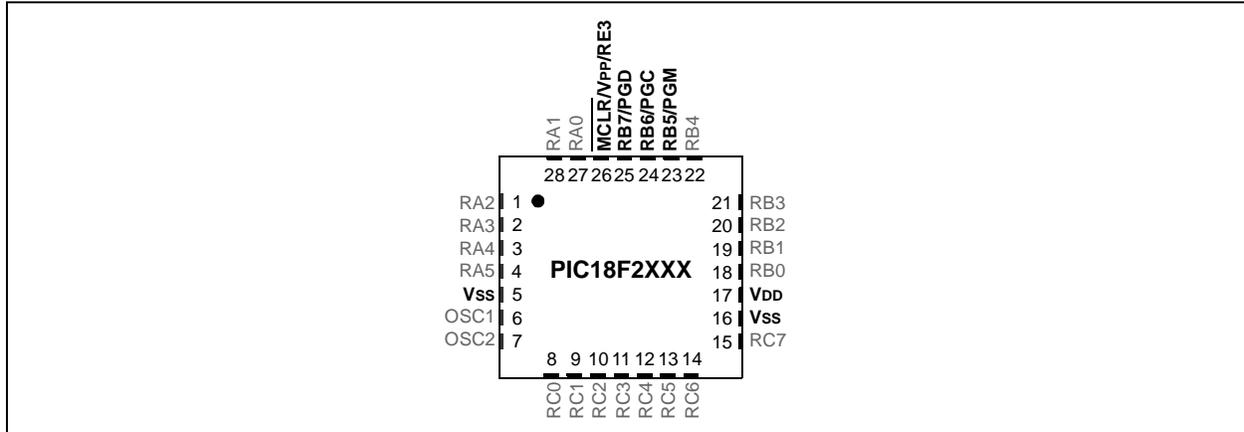
The following devices are included in 40-pin PDIP parts:

- PIC18F4221
- PIC18F4321
- PIC18F4410
- PIC18F4420
- PIC18F4423
- PIC18F4450

- PIC18F4455
- PIC18F4458
- PIC18F4480
- PIC18F4510
- PIC18F4515
- PIC18F4520

- PIC18F4523
- PIC18F4525
- PIC18F4550
- PIC18F4553
- PIC18F4580
- PIC18F4585

- PIC18F4610
- PIC18F4620
- PIC18F4680
- PIC18F4682
- PIC18F4685

FIGURE 2-3:   40-Pin PDIP
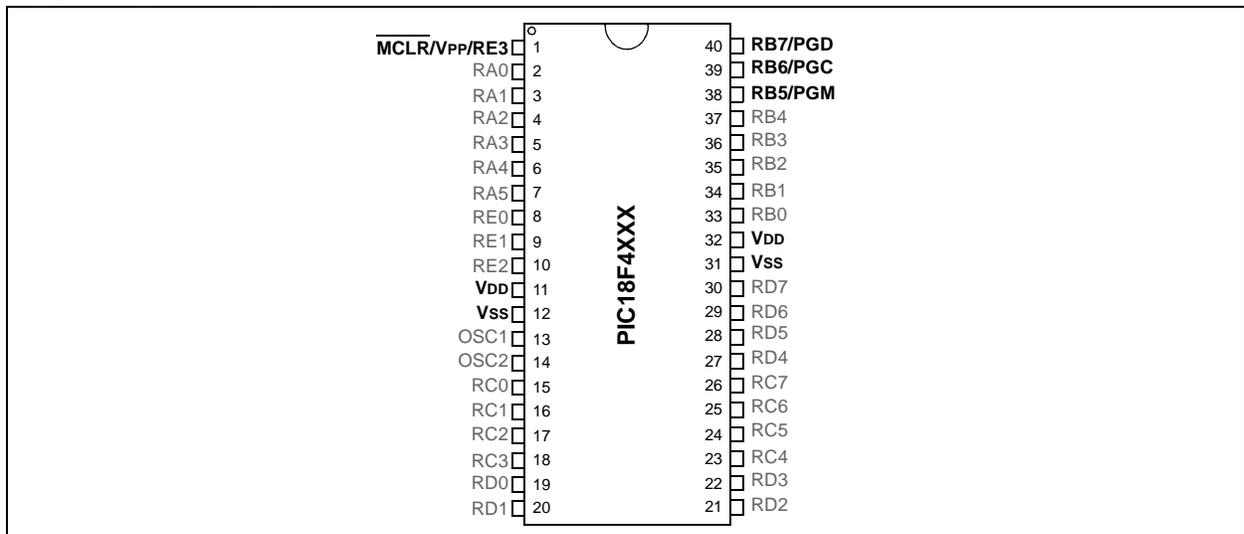
TABLE 2-2: **IMPLEMENTATION OF CODE MEMORY**

Device	Code Memory Size (Bytes)
PIC18F2515	000000h-00BFFFh (48K)
PIC18F2525	
PIC18F2585	
PIC18F4515	
PIC18F4525	
PIC18F4585	
PIC18F2610	000000h-00FFFFh (64K)
PIC18F2620	
PIC18F2680	
PIC18F4610	
PIC18F4620	
PIC18F4680	

FIGURE 2-6: **MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18FX5X5/X6X0 DEVICES**

Note: Sizes of memory areas are not to scale.

* Boot Block size is determined by the BBSIZ<1:0> bits in the CONFIG4L register.
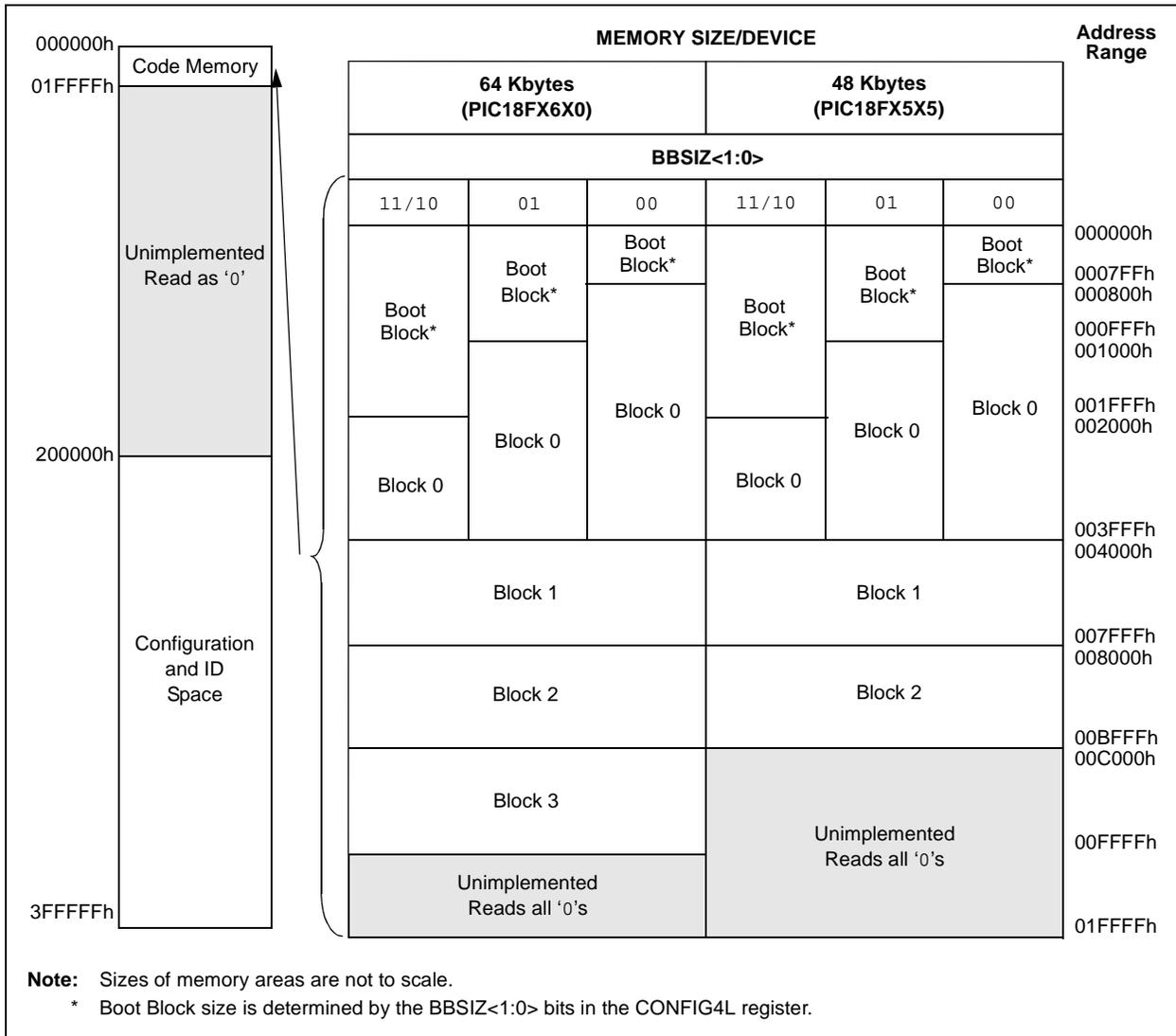
PIC18F2XXX/4XXX FAMILY

The size of the Boot Block in PIC18F2221/2321/4221/4321 devices can be configured as 256, 512 or 1024 words (see Figure 2-11). This is done through the BBSIZ<1:0> bits in the Configuration register, CONFIG4L (see Figure 2-11). It is important to note that increasing the size of the Boot Block decreases the size of Block 0.

TABLE 2-7:   IMPLEMENTATION OF CODE MEMORY

Device	Code Memory Size (Bytes)
PIC18F2221	000000h-000FFFh (4K)
PIC18F4221	
PIC18F2321	000000h-001FFFh (8K)
PIC18F4321	

FIGURE 2-11:   MEMORY MAP AND THE CODE MEMORY SPACE
FOR PIC18F2221/2321/4221/4321 DEVICES

Note: Sizes of memory areas are not to scale.

    * Boot Block size is determined by the BBSIZ<1:0> bits in the CONFIG4L register.
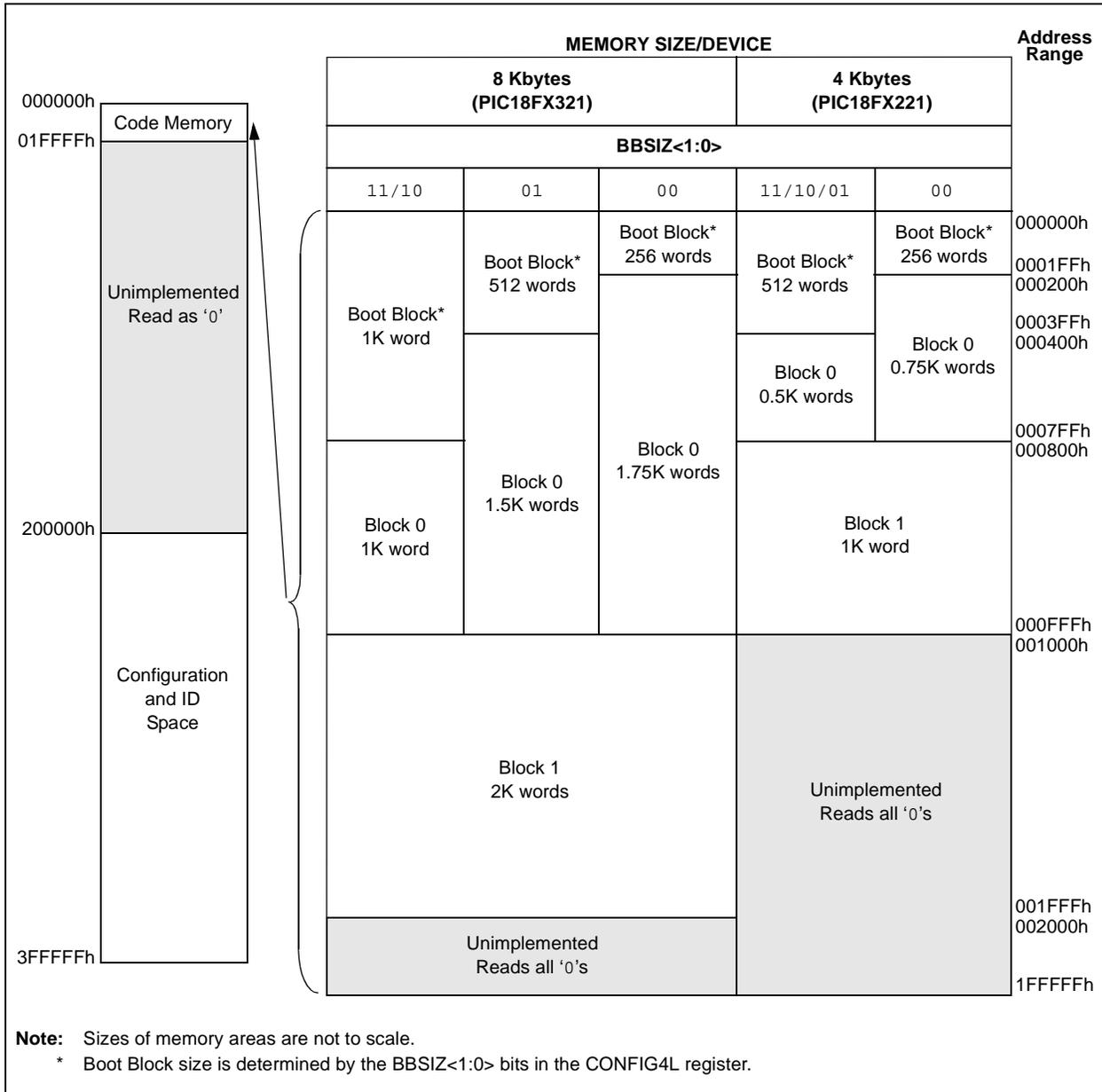
2.4   High-Level Overview of the Programming Process

Figure 2-13 shows the high-level overview of the programming process. First, a Bulk Erase is performed. Next, the code memory, ID locations and data EEPROM are programmed (selected devices only, see **Section 3.3 "Data EEPROM Programming"**). These memories are then verified to ensure that programming was successful. If no errors are detected, the Configuration bits are then programmed and verified.

**FIGURE 2-13:   HIGH-LEVEL PROGRAMMING FLOW**

```
                    ┌──────────┐
                    │  Start   │
                    └──────────┘
                         │
              ┌──────────────────────┐
              │    Perform Bulk      │
              │        Erase         │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │    Program Memory     │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │     Program IDs       │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │  Program Data EE(1)    │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │    Verify Program     │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │      Verify IDs       │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │      Verify Data      │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │       Program         │
              │  Configuration Bits   │
              └──────────────────────┘
                         │
              ┌──────────────────────┐
              │        Verify         │
              │  Configuration Bits   │
              └──────────────────────┘
                         │
                    ┌──────────┐
                    │   Done   │
                    └──────────┘
```

Note 1:   Selected devices only, see **Section 3.3 "Data EEPROM Programming"**.
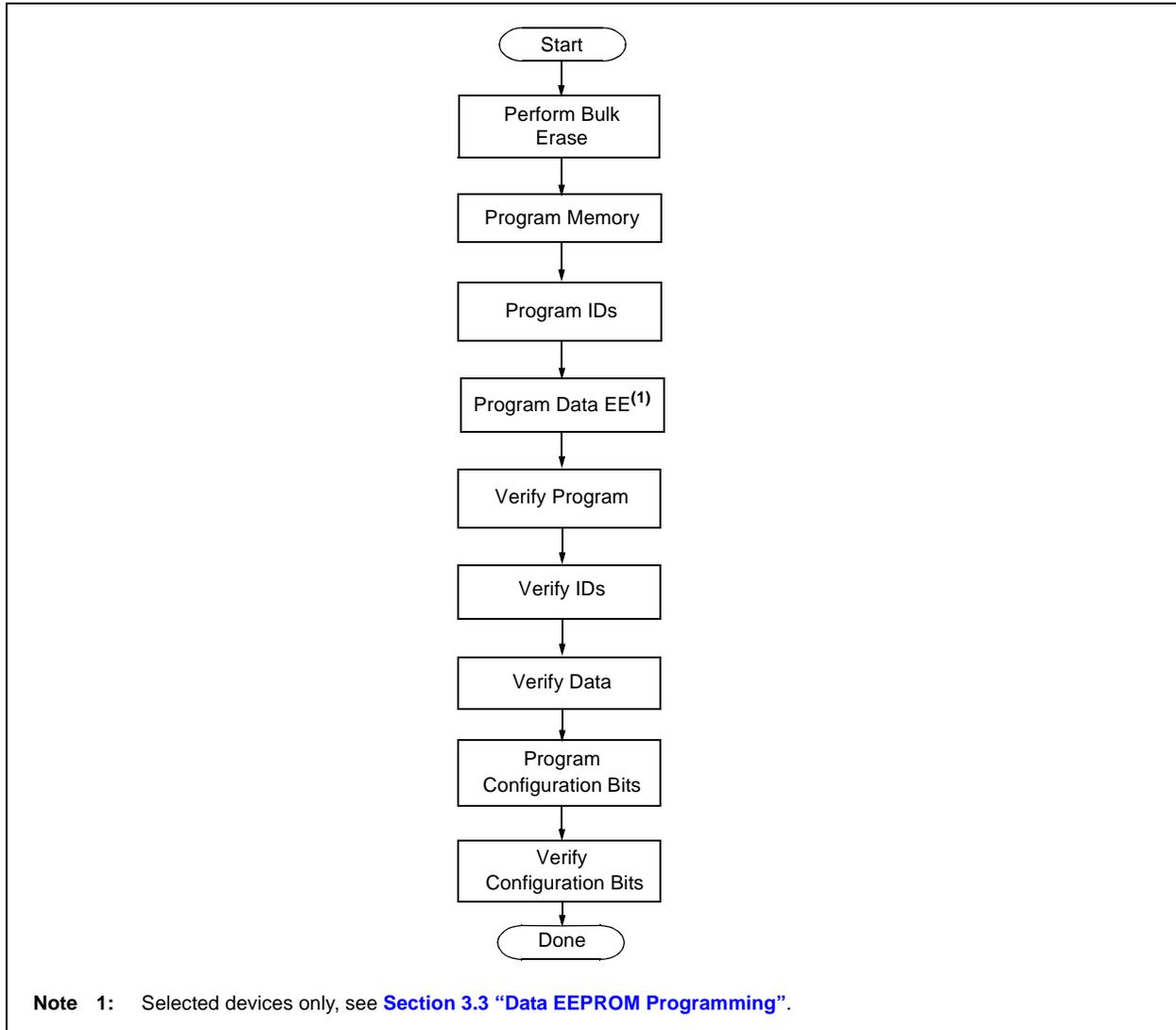
TABLE 3-2: **BULK ERASE COMMAND SEQUENCE**

4-Bit Command	Data Payload	Core Instruction
0000	0E 3C	MOVLW 3Ch
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 05	MOVLW 05h
0000	6E F6	MOVWF TBLPTRL
1100	3F 3F	Write 3F3Fh to 3C0005h
0000	0E 3C	MOVLW 3Ch
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 04	MOVLW 04h
0000	6E F6	MOVWF TBLPTRL
1100	8F 8F	Write 8F8Fh TO 3C0004h to erase entire device.
		NOP
		Hold PGD low until erase completes.
0000	00 00	
0000	00 00	

FIGURE 3-1: **BULK ERASE FLOW**

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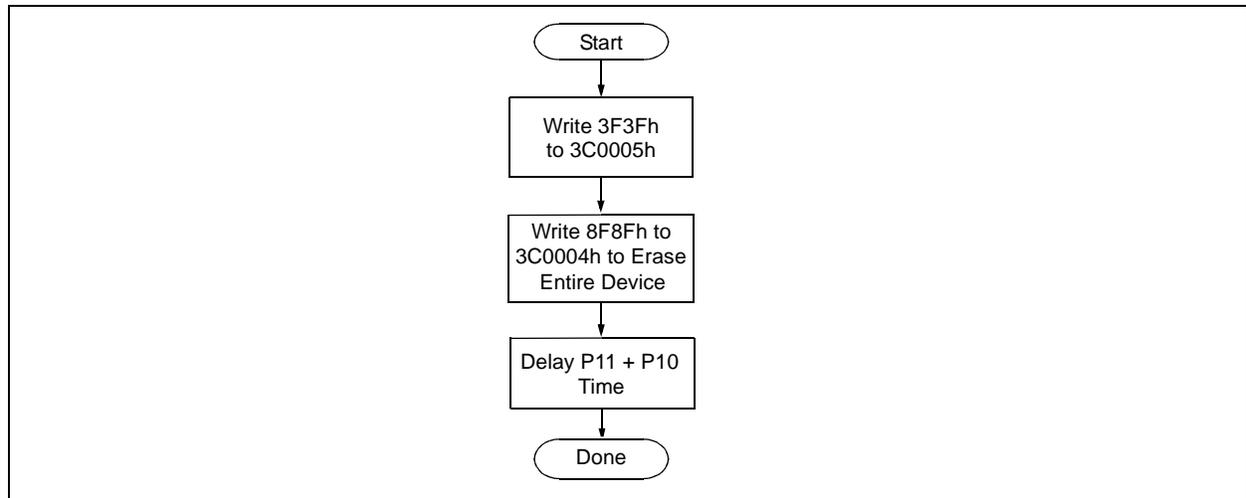
3.1.2 LOW-VOLTAGE ICSP BULK ERASE

When using low-voltage ICSP, the part must be supplied by the voltage specified in Parameter D111 if a Bulk Erase is to be executed. All other Bulk Erase details, as described above, apply.

If it is determined that a program memory erase must be performed at a supply voltage below the Bulk Erase limit, refer to the erase methodology described in **Section 3.1.3 "ICSP Row Erase"** and **Section 3.2.1 "Modifying Code Memory"**.

If it is determined that a data EEPROM erase (selected devices only, see **Section 3.3 "Data EEPROM Programming"**) must be performed at a supply voltage below the Bulk Erase limit, follow the methodology described in **Section 3.3 "Data EEPROM Programming"** and write '1's to the array.

FIGURE 3-2: **BULK ERASE TIMING**
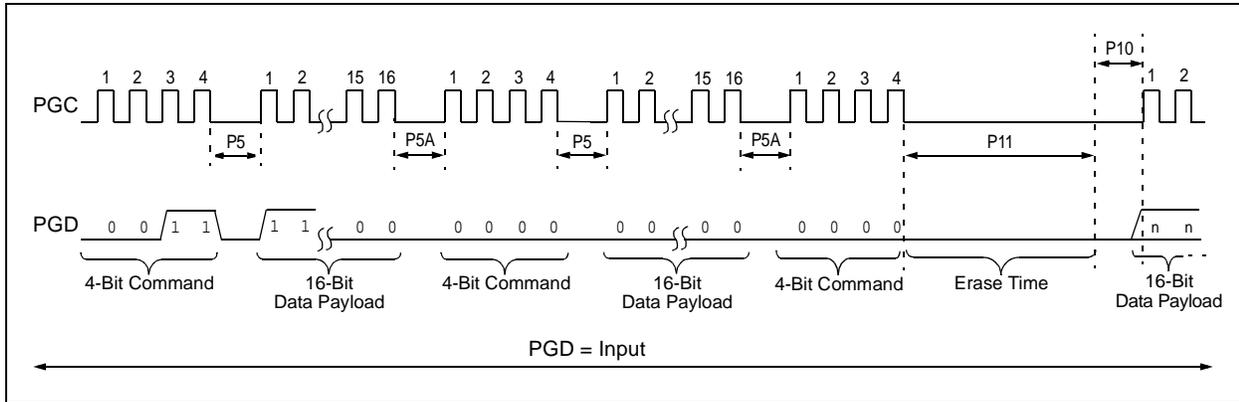
3.1.3 ICSP ROW ERASE

Regardless of whether high or low-voltage ICSP is used, it is possible to erase one row (64 bytes of data), provided the block is not code or write-protected. Rows are located at static boundaries, beginning at program memory address, 000000h, extending to the internal program memory limit (see **Section 2.3 "Memory Maps"**).

The Row Erase duration is externally timed and is controlled by PGC. After the WR bit in EECON1 is set, a NOP is issued, where the 4th PGC is held high for the duration of the programming time, P9.

After PGC is brought low, the programming sequence is terminated. PGC must be held low for the time specified by Parameter P10 to allow high-voltage discharge of the memory array.

The code sequence to Row Erase a PIC18F2XXX/4XXX Family device is shown in Table 3-3. The flowchart, shown in Figure 3-3, depicts the logic necessary to completely erase a PIC18F2XXX/4XXX Family device. The timing diagram that details the Start Programming command and Parameters P9 and P10 is shown in Figure 3-5.

Note:	The TBLPTR register can point to any byte within the row intended for erase.

3.2.1   MODIFYING CODE MEMORY

The previous programming example assumed that the device had been Bulk Erased prior to programming (see **Section 3.1.1 "High-Voltage ICSP Bulk Erase"**). It may be the case, however, that the user wishes to modify only a section of an already programmed device.

The appropriate number of bytes required for the erase buffer must be read out of code memory (as described in **Section 4.2 "Verify Code Memory and ID Locations"**) and buffered. Modifications can be made on this buffer. Then, the block of code memory that was read out must be erased and rewritten with the modified data.

The WREN bit must be set if the WR bit in EECON1 is used to initiate a write sequence.

TABLE 3-6:   MODIFYING CODE MEMORY

4-Bit Command	Data Payload	Core Instruction
Step 1: Direct access to code memory.		
Step 2: Read and modify code memory (see **Section 4.1 "Read Code Memory, ID Locations and Configuration Bits"**).		
0000 0000	8E A6 9C A6	BSF EECON1, EEPGD BCF EECON1, CFGS
Step 3: Set the Table Pointer for the block to be erased.		
0000 0000 0000 0000 0000 0000	0E <Addr[21:16]> 6E F8 0E <Addr[8:15]> 6E F7 0E <Addr[7:0]> 6E F6	MOVLW <Addr[21:16]> MOVWF TBLPTRU MOVLW <Addr[8:15]> MOVWF TBLPTRH MOVLW <Addr[7:0]> MOVWF TBLPTRL
Step 4: Enable memory writes and set up an erase.		
0000 0000	84 A6 88 A6	BSF EECON1, WREN BSF EECON1, FREE
Step 5: Initiate erase.		
0000 0000	82 A6 00 00	BSF EECON1, WR NOP - hold PGC high for time P9 and low for time P10.
Step 6: Load write buffer. The correct bytes will be selected based on the Table Pointer.		
0000 0000 0000 0000 0000 0000 1101 . . . 1111 0000	0E <Addr[21:16]> 6E F8 0E <Addr[8:15]> 6E F7 0E <Addr[7:0]> 6E F6 <MSB><LSB> . . . <MSB><LSB> 00 00	MOVLW <Addr[21:16]> MOVWF TBLPTRU MOVLW <Addr[8:15]> MOVWF TBLPTRH MOVLW <Addr[7:0]> MOVWF TBLPTRL Write 2 bytes and post-increment address by 2. Repeat as many times as necessary to fill the write buffer Write 2 bytes and start programming. NOP - hold PGC high for time P9 and low for time P10.
To continue modifying data, repeat Steps 2 through 6, where the Address Pointer is incremented by the appropriate number of bytes (see Table 3-4) at each iteration of the loop. The write cycle must be repeated enough times to completely rewrite the contents of the erase buffer.		
Step 7: Disable writes.		
0000	94 A6	BCF EECON1, WREN

4.4 Read Data EEPROM Memory

Data EEPROM is accessed, one byte at a time, via an Address Pointer (register pair: EEADRH:EEADR) and a data latch (EEDATA). Data EEPROM is read by loading EEADRH:EEADR with the desired memory location and initiating a memory read by appropriately configuring the EECON1 register. The data will be loaded into EEDATA, where it may be serially output on PGD via the 4-bit command, '0010' (Shift Out Data Holding register). A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an input to an output. During this time, PGC must be held low (see Figure 4-4).

The command sequence to read a single byte of data is shown in Table 4-2.

FIGURE 4-3: **READ DATA EEPROM FLOW**
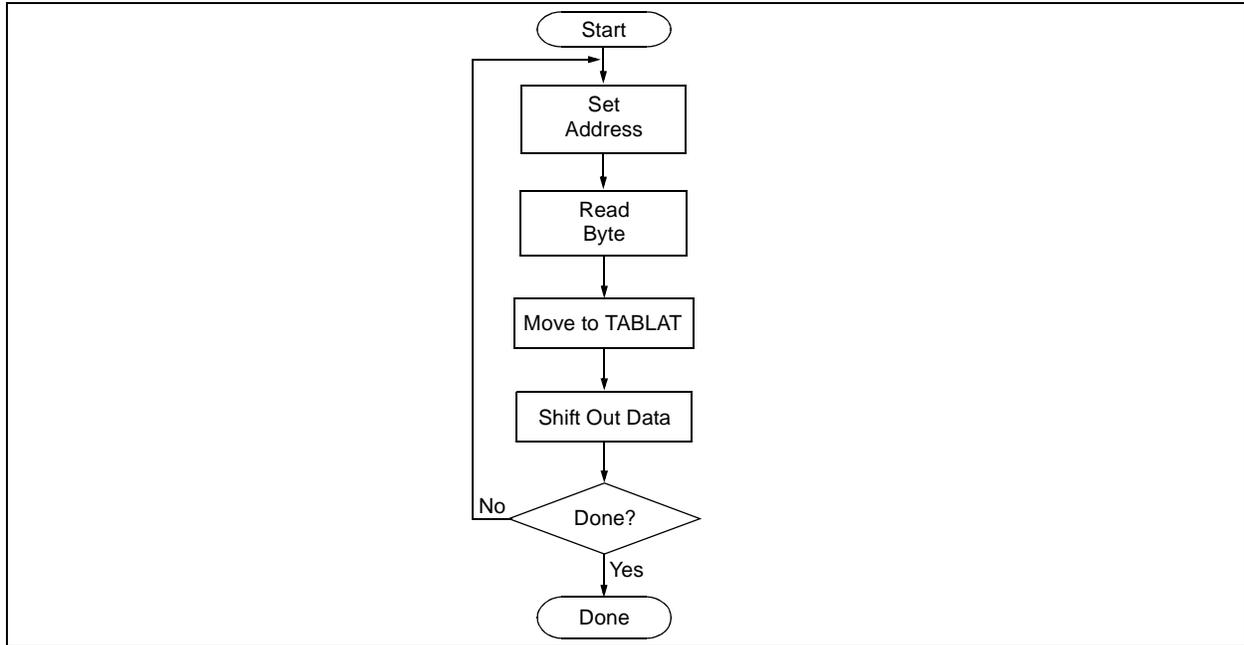
TABLE 4-2: **READ DATA EEPROM MEMORY**

4-Bit Command	Data Payload	Core Instruction
Step 1: Direct access to data EEPROM.		
0000 0000	9E A6 9C A6	BCF EECON1, EEPGD BCF EECON1, CFGS
Step 2: Set the data EEPROM Address Pointer.		
0000 0000 0000 0000	0E \<Addr> 6E A9 OE \<AddrH> 6E AA	MOVLW \<Addr> MOVWF EEADR MOVLW \<AddrH> MOVWF EEADRH
Step 3: Initiate a memory read.		
0000	80 A6	BSF EECON1, RD
Step 4: Load data into the Serial Data Holding register.		
0000 0000 0000 0010	50 A8 6E F5 00 00 \<MSB>\<LSB>	MOVF EEDATA, W, 0 MOVWF TABLAT NOP Shift Out Data[1]

Note   1: The \<LSB> is undefined. The \<MSB> is the data.

FIGURE 4-4: SHIFT OUT DATA HOLDING REGISTER TIMING (`0010`)
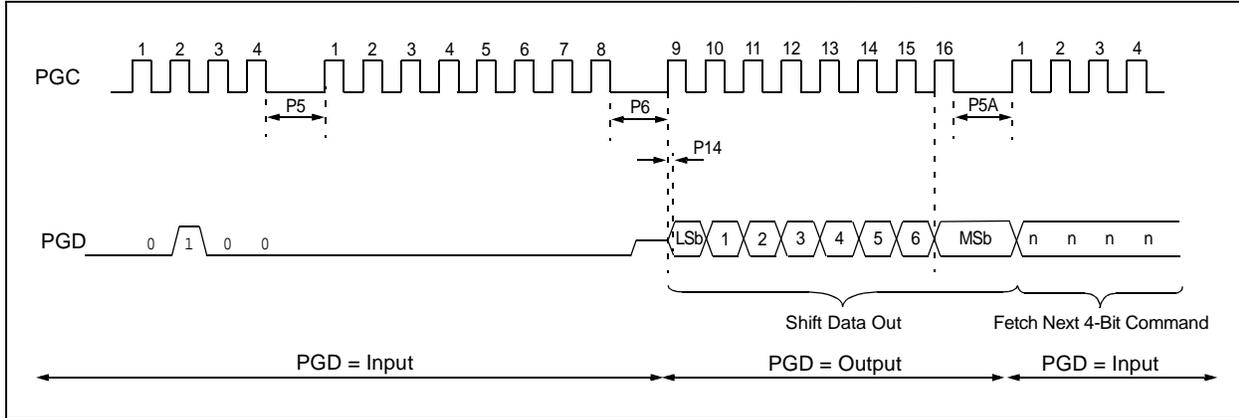
4.5 Verify Data EEPROM

A data EEPROM address may be read via a sequence of core instructions (4-bit command, '`0000`') and then output on PGD via the 4-bit command, '`0010`' (TABLAT register). The result may then be immediately compared to the appropriate data in the programmer's memory for verification. Refer to **Section 4.4 "Read Data EEPROM Memory"** for implementation details of reading data EEPROM.

4.6 Blank Check

The term Blank Check means to verify that the device has no programmed memory cells. All memories must be verified: code memory, data EEPROM, ID locations and Configuration bits. The Device ID registers (3FFFFEh:3FFFFFh) should be ignored.

A "blank" or "erased" memory cell will read as '1'. Therefore, Blank Checking a device merely means to verify that all bytes read as FFh, except the Configuration bits. Unused (reserved) Configuration bits will read '`0`' (programmed). Refer to Figure 4-5 for blank configuration expect data for the various PIC18F2XXX/4XXX Family devices.

Given that Blank Checking is merely code and data EEPROM verification with FFh expect data, refer to **Section 4.4 "Read Data EEPROM Memory"** and **Section 4.2 "Verify Code Memory and ID Locations"** for implementation details.

FIGURE 4-5: BLANK CHECK FLOW
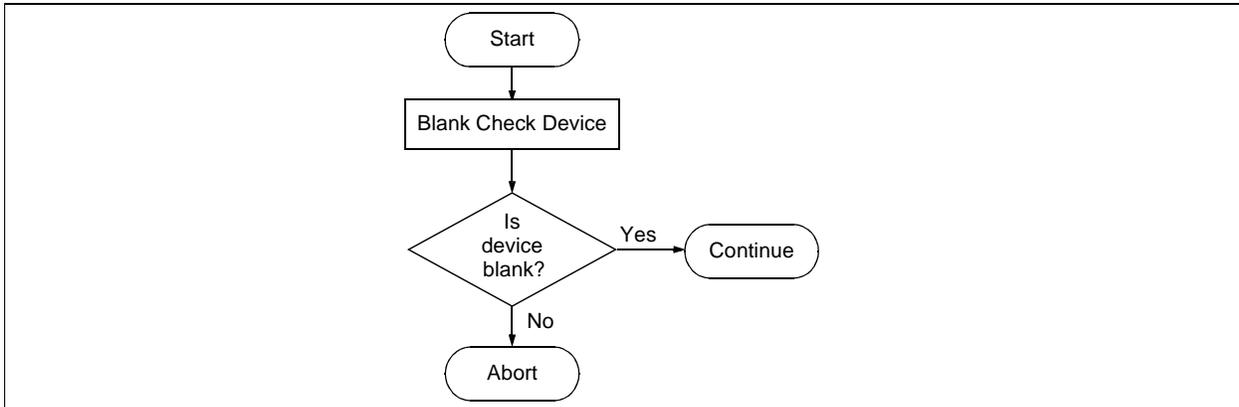
TABLE 5-2:   DEVICE ID VALUES

Device	Device ID Value	
	DEVID2	**DEVID1**
PIC18F2221	21h	011x xxxx
PIC18F2321	21h	001x xxxx
PIC18F2410	11h	011x xxxx
PIC18F2420	11h	010x xxxx[1]
PIC18F2423	11h	010x xxxx[2]
PIC18F2450	24h	001x xxxx
PIC18F2455	12h	011x xxxx
PIC18F2458	2Ah	011x xxxx
PIC18F2480	1Ah	111x xxxx
PIC18F2510	11h	001x xxxx
PIC18F2515	0Ch	111x xxxx
PIC18F2520	11h	000x xxxx[1]
PIC18F2523	11h	000x xxxx[2]
PIC18F2525	0Ch	110x xxxx
PIC18F2550	12h	010x xxxx
PIC18F2553	2Ah	010x xxxx
PIC18F2580	1Ah	110x xxxx
PIC18F2585	0Eh	111x xxxx
PIC18F2610	0Ch	101x xxxx
PIC18F2620	0Ch	100x xxxx
PIC18F2680	0Eh	110x xxxx
PIC18F2682	27h	000x xxxx
PIC18F2685	27h	001x xxxx
PIC18F4221	21h	010x xxxx
PIC18F4321	21h	000x xxxx
PIC18F4410	10h	111x xxxx
PIC18F4420	10h	110x xxxx[1]
PIC18F4423	10h	110x xxxx[2]
PIC18F4450	24h	000x xxxx
PIC18F4455	12h	001x xxxx
PIC18F4458	2Ah	001x xxxx
PIC18F4480	1Ah	101x xxxx
PIC18F4510	10h	101x xxxx
PIC18F4515	0Ch	011x xxxx
PIC18F4520	10h	100x xxxx[1]
PIC18F4523	10h	100x xxxx[2]
PIC18F4525	0Ch	010x xxxx
PIC18F4550	12h	000x xxxx
PIC18F4553	2Ah	000x xxxx
PIC18F4580	1Ah	100x xxxx

Legend: The 'x's in DEVID1 contain the device revision code.
Note 1:   DEVID1 bit 4 is used to determine the device type (REV4 = 0).
          2:   DEVID1 bit 4 is used to determine the device type (REV4 = 1).

TABLE 5-3: PIC18F2XXX/4XXX FAMILY BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Words	Description
WDTEN	CONFIG2H	Watchdog Timer Enable bit `1` = WDT is enabled `0` = WDT is disabled (control is placed on the SWDTEN bit)
MCLRE	CONFIG3H	MCLR Pin Enable bit `1` = MCLR pin is enabled, RE3 input pin is disabled `0` = RE3 input pin is enabled, MCLR pin is disabled
LPT1OSC	CONFIG3H	Low-Power Timer1 Oscillator Enable bit `1` = Timer1 is configured for low-power operation `0` = Timer1 is configured for high-power operation
PBADEN	CONFIG3H	PORTB A/D Enable bit `1` = PORTB A/D<4:0> pins are configured as analog input channels on Reset `0` = PORTB A/D<4:0> pins are configured as digital I/O on Reset
PBADEN	CONFIG3H	PORTB A/D Enable bit **(PIC18FXX8X devices only)** `1` = PORTB A/D<4:0> and PORTB A/D<1:0> pins are configured as analog input channels on Reset `0` = PORTB A/D<4:0> pins are configured as digital I/O on Reset
CCP2MX	CONFIG3H	CCP2 MUX bit `1` = CCP2 input/output is multiplexed with RC1[2] `0` = CCP2 input/output is multiplexed with RB3
DEBUG	CONFIG4L	Background Debugger Enable bit `1` = Background debugger is disabled, RB6 and RB7 are configured as general purpose I/O pins `0` = Background debugger is enabled, RB6 and RB7 are dedicated to In-Circuit Debug
XINST	CONFIG4L	Extended Instruction Set Enable bit `1` = Instruction set extension and Indexed Addressing mode are enabled `0` = Instruction set extension and Indexed Addressing mode are disabled (Legacy mode)
ICPRT	CONFIG4L	Dedicated In-Circuit (ICD/ICSP™) Port Enable bit **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** `1` = ICPORT is enabled `0` = ICPORT is disabled
BBSIZ<1:0>[1]	CONFIG4L	Boot Block Size Select bits **(PIC18F2585/2680/4585/4680 devices only)** `11` = 4K words (8 Kbytes) Boot Block `10` = 4K words (8 Kbytes) Boot Block `01` = 2K words (4 Kbytes) Boot Block `00` = 1K word (2 Kbytes) Boot Block
BBSIZ<2:1>[1]	CONFIG4L	Boot Block Size Select bits **(PIC18F2682/2685/4582/4685 devices only)** `11` = 4K words (8 Kbytes) Boot Block `10` = 4K words (8 Kbytes) Boot Block `01` = 2K words (4 Kbytes) Boot Block `00` = 1K word (2 Kbytes) Boot Block

Note 1: The BBSIZ bits, BBSIZ<1:0> and BBSIZ<2:1> bits, cannot be changed once any of the following code-protect bits are enabled: CPB or CP0, WRTB or WRT0, EBTRB or EBTR0.

2: Not available in PIC18FXX8X and PIC18F2450/4450 devices.

TABLE 5-3: PIC18F2XXX/4XXX FAMILY BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Words	Description
EBTR0	CONFIG7L	Table Read Protection bit (Block 0 code memory area) 1 = Block 0 is not protected from Table Reads executed in other blocks 0 = Block 0 is protected from Table Reads executed in other blocks
EBTRB	CONFIG7H	Table Read Protection bit (Boot Block memory area) 1 = Boot Block is not protected from Table Reads executed in other blocks 0 = Boot Block is protected from Table Reads executed in other blocks
DEV<10:3>	DEVID2	Device ID bits These bits are used with the DEV<2:0> bits in the DEVID1 register to identify part number.
DEV<2:0>	DEVID1	Device ID bits These bits are used with the DEV<10:3> bits in the DEVID2 register to identify part number.
REV<4:0>	DEVID1	Revision ID bits These bits are used to indicate the revision of the device. The REV4 bit is sometimes used to fully specify the device type.

Note 1: The BBSIZ bits, BBSIZ<1:0> and BBSIZ<2:1> bits, cannot be changed once any of the following code-protect bits are enabled: CPB or CP0, WRTB or WRT0, EBTRB or EBTR0.

2: Not available in PIC18FXX8X and PIC18F2450/4450 devices.

5.3 Single-Supply ICSP Programming

The LVP bit in Configuration register, CONFIG4L, enables Single-Supply (Low-Voltage) ICSP Programming. The LVP bit defaults to a '1' (enabled) from the factory.

If Single-Supply Programming mode is not used, the LVP bit can be programmed to a '0' and RB5/PGM becomes a digital I/O pin. However, the LVP bit may only be programmed by entering the High-Voltage ICSP mode, where MCLR/VPP/RE3 is raised to VIHH. Once the LVP bit is programmed to a '0', only the High-Voltage ICSP mode is available and only the High-Voltage ICSP mode can be used to program the device.

> **Note 1:** The High-Voltage ICSP mode is always available, regardless of the state of the LVP bit, by applying VIHH to the MCLR/VPP/RE3 pin.
>
> **2:** While in Low-Voltage ICSP mode, the RB5 pin can no longer be used as a general purpose I/O.

5.4 Embedding Configuration Word Information in the HEX File

To allow portability of code, a PIC18F2XXX/4XXX Family programmer is required to read the Configuration Word locations from the hex file. If Configuration Word information is not present in the hex file, then a simple warning message should be issued. Similarly, while saving a hex file, all Configuration Word information must be included. An option to not include the Configuration Word information may be provided. When embedding Configuration Word information in the hex file, it should start at address, 300000h.

Microchip Technology Inc. feels strongly that this feature is important for the benefit of the end customer.

5.5 Embedding Data EEPROM Information In the HEX File

To allow portability of code, a PIC18F2XXX/4XXX Family programmer is required to read the data EEPROM information from the hex file. If data EEPROM information is not present, a simple warning message should be issued. Similarly, when saving a hex file, all data EEPROM information must be included. An option to not include the data EEPROM information may be provided. When embedding data EEPROM information in the hex file, it should start at address, F00000h.

Microchip Technology Inc. believes that this feature is important for the benefit of the end customer.

5.6 Checksum Computation

The checksum is calculated by summing the following:

• The contents of all code memory locations
• The Configuration Words, appropriately masked
• ID locations (if any block is code-protected)

The Least Significant 16 bits of this sum is the checksum. The contents of the data EEPROM are not used.

5.6.1 PROGRAM MEMORY

When program memory contents are summed, each 16-bit word is added to the checksum. The contents of program memory, from 000000h to the end of the last program memory block, are used for this calculation. Overflows from bit 15 may be ignored.

5.6.2 CONFIGURATION WORDS

For checksum calculations, unimplemented bits in Configuration Words should be ignored as such bits always read back as '1's. Each 8-bit Configuration Word is ANDed with a corresponding mask to prevent unused bits from affecting checksum calculations.

The mask contains a '0' in unimplemented bit positions, or a '1' where a choice can be made. When ANDed with the value read out of a Configuration Word, only implemented bits remain. A list of suitable masks is provided in Table 5-5.

5.6.3   ID LOCATIONS

Normally, the contents of these locations are defined by the user, but MPLAB® IDE provides the option of writing the device's unprotected 16-bit checksum in the 16 Most Significant bits of the ID locations (see MPLAB IDE Configure/ID Memory" menu). The lower 16 bits are not used and remain clear. This is the sum of all program memory contents and Configuration Words (appropriately masked) before any code protection is enabled.

If the user elects to define the contents of the ID locations, nothing about protected blocks can be known. If the user uses the preprotected checksum, provided by MPLAB IDE, an indirect characteristic of the programmed code is provided.

5.6.4   CODE PROTECTION

Blocks that are code-protected read back as all '0's and have no effect on checksum calculations. If any block is code-protected, then the contents of the ID locations are included in the checksum calculation.

All Configuration Words and the ID locations can always be read out normally, even when the device is fully code-protected. Checking the code protection settings in Configuration Words can direct which, if any, of the program memory blocks can be read, and if the ID locations should be used for checksum calculations.

TABLE 5-5: **CONFIGURATION WORD MASKS FOR COMPUTING CHECKSUMS**

Device	Configuration Word (CONFIGxx)													
	1L	1H	2L	2H	3L	3H	4L	4H	5L	5H	6L	6H	7L	7H
	Address (30000xh)													
	0h	1h	2h	3h	4h	5h	6h	7h	8h	9h	Ah	Bh	Ch	Dh
PIC18F2221	00	CF	1F	1F	00	87	F5	00	03	C0	03	E0	03	40
PIC18F2321	00	CF	1F	1F	00	87	F5	00	03	C0	03	E0	03	40
PIC18F2410	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F2420	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F2423	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F2450	3F	CF	3F	1F	00	86	ED	00	03	40	03	60	03	40
PIC18F2455	3F	CF	3F	1F	00	87	E5	00	07	C0	07	E0	07	40
PIC18F2458	3F	CF	3F	1F	00	87	E5	00	07	C0	07	E0	07	40
PIC18F2480	00	CF	1F	1F	00	86	D5	00	03	C0	03	E0	03	40
PIC18F2510	00	1F	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2515	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2520	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2523	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2525	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2550	3F	CF	3F	1F	00	87	E5	00	0F	C0	0F	E0	0F	40
PIC18F2553	3F	CF	3F	1F	00	87	E5	00	0F	C0	0F	E0	0F	40
PIC18F2580	00	CF	1F	1F	00	86	D5	00	0F	C0	0F	E0	0F	40
PIC18F2585	00	CF	1F	1F	00	86	C5	00	0F	C0	0F	E0	0F	40
PIC18F2610	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2620	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F2680	00	CF	1F	1F	00	86	C5	00	0F	C0	0F	E0	0F	40
PIC18F2682	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40
PIC18F2685	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40
PIC18F4221	00	CF	1F	1F	00	87	F5	00	03	C0	03	E0	03	40
PIC18F4321	00	CF	1F	1F	00	87	F5	00	03	C0	03	E0	03	40
PIC18F4410	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F4420	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F4423	00	CF	1F	1F	00	87	C5	00	03	C0	03	E0	03	40
PIC18F4450	3F	CF	3F	1F	00	86	ED	00	03	40	03	60	03	40
PIC18F4455	3F	CF	3F	1F	00	87	E5	00	07	C0	07	E0	07	40
PIC18F4458	3F	CF	3F	1F	00	87	E5	00	07	C0	07	E0	07	40
PIC18F4480	00	CF	1F	1F	00	86	D5	00	03	C0	03	E0	03	40
PIC18F4510	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4515	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4520	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4523	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4525	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4550	3F	CF	3F	1F	00	87	E5	00	0F	C0	0F	E0	0F	40
PIC18F4553	3F	CF	3F	1F	00	87	E5	00	0F	C0	0F	E0	0F	40
PIC18F4580	00	CF	1F	1F	00	86	D5	00	0F	C0	0F	E0	0F	40
PIC18F4585	00	CF	1F	1F	00	86	C5	00	0F	C0	0F	E0	0F	40
PIC18F4610	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40

Legend: Shaded cells are unimplemented.

TABLE 5-5: **CONFIGURATION WORD MASKS FOR COMPUTING CHECKSUMS (CONTINUED)**

Device	Configuration Word (CONFIGxx)													
	1L	1H	2L	2H	3L	3H	4L	4H	5L	5H	6L	6H	7L	7H
	Address (30000xh)													
	0h	1h	2h	3h	4h	5h	6h	7h	8h	9h	Ah	Bh	Ch	Dh
PIC18F4620	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4680	00	CF	1F	1F	00	86	C5	00	0F	C0	0F	E0	0F	40
PIC18F4682	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40
PIC18F4685	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40

Legend: Shaded cells are unimplemented.

6.0   AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY TEST MODE

Standard Operating Conditions
Operating Temperature: 25°C is recommended

Param No.	Sym	Characteristic	Min	Max	Units	Conditions
D110	VIHH	High-Voltage Programming Voltage on MCLR/VPP/RE3	VDD + 4.0	12.5	V	**(Note 2)**
D110A	VIHL	Low-Voltage Programming Voltage on MCLR/VPP/RE3	2.00	5.50	V	**(Note 2)**
D111	VDD	Supply Voltage During Programming	2.00	5.50	V	Externally timed, Row Erases and all writes
			3.0	5.50	V	Self-timed, Bulk Erases only **(Note 3)**
D112	IPP	Programming Current on MCLR/VPP/RE3	—	300	μA	**(Note 2)**
D113	IDDP	Supply Current During Programming	—	10	mA	
D031	VIL	Input Low Voltage	VSS	0.2 VDD	V	
D041	VIH	Input High Voltage	0.8 VDD	VDD	V	
D080	VOL	Output Low Voltage	—	0.6	V	IOL = 8.5 mA @ 4.5V
D090	VOH	Output High Voltage	VDD – 0.7	—	V	IOH = -3.0 mA @ 4.5V
D012	CIO	Capacitive Loading on I/O pin (PGD)	—	50	pF	To meet AC specifications
P1	TR	MCLR/VPP/RE3 Rise Time to Enter Program/Verify mode	—	1.0	μs	**(Notes 1, 2)**
P2	TPGC	Serial Clock (PGC) Period	100	—	ns	VDD = 5.0V
			1	—	μs	VDD = 2.0V
P2A	TPGCL	Serial Clock (PGC) Low Time	40	—	ns	VDD = 5.0V
			400	—	ns	VDD = 2.0V
P2B	TPGCH	Serial Clock (PGC) High Time	40	—	ns	VDD = 5.0V
			400	—	ns	VDD = 2.0V
P3	TSET1	Input Data Setup Time to Serial Clock ↓	15	—	ns	
P4	THLD1	Input Data Hold Time from PGC ↓	15	—	ns	
P5	TDLY1	Delay Between 4-Bit Command and Command Operand	40	—	ns	
P5A	TDLY1A	Delay Between 4-Bit Command Operand and Next 4-Bit Command	40	—	ns	
P6	TDLY2	Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word	20	—	ns	
P9	TDLY5	PGC High Time (minimum programming time)	1	—	ms	Externally timed
P10	TDLY6	PGC Low Time After Programming (high-voltage discharge time)	100	—	μs	
P11	TDLY7	Delay to Allow Self-Timed Data Write or Bulk Erase to Occur	5	—	ms	

Note 1: Do not allow excess time when transitioning MCLR between VIL and VIHH. This can cause spurious program executions to occur. The maximum transition time is:

1 TCY + TPWRT (if enabled) + 1024 TOSC (for LP, HS, HS/PLL and XT modes only) +

2 ms (for HS/PLL mode only) + 1.5 μs (for EC mode only)

where TCY is the instruction cycle time, TPWRT is the Power-up Timer period and TOSC is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.

2: When ICPRT = 1, this specification also applies to ICVPP.

3: At 0°C-50°C.

6.0 AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY TEST MODE (CONTINUED)

Standard Operating Conditions
Operating Temperature: 25°C is recommended

Param No.	Sym	Characteristic	Min	Max	Units	Conditions
P11A	T_{DRWT}	Data Write Polling Time	4	—	ms	
P12	T_{HLD2}	Input Data Hold Time from $\overline{MCLR}$/VPP/RE3 ↑	2	—	μs	
P13	T_{SET2}	VDD ↑ Setup Time to $\overline{MCLR}$/VPP/RE3 ↑	100	—	ns	**(Note 2)**
P14	T_{VALID}	Data Out Valid from PGC ↑	10	—	ns	
P15	T_{SET3}	PGM ↑ Setup Time to $\overline{MCLR}$/VPP/RE3 ↑	2	—	μs	**(Note 2)**
P16	T_{DLY8}	Delay Between Last PGC ↓ and $\overline{MCLR}$/VPP/RE3 ↓	0	—	s	
P17	T_{HLD3}	$\overline{MCLR}$/VPP/RE3 ↓ to VDD ↓	—	100	ns	
P18	T_{HLD4}	$\overline{MCLR}$/VPP/RE3 ↓ to PGM ↓	0	—	s	

Note 1: Do not allow excess time when transitioning $\overline{MCLR}$ between V_{IL} and V_{IHH}. This can cause spurious program executions to occur. The maximum transition time is:

    1 T_{CY} + T_{PWRT} (if enabled) + 1024 T_{OSC} (for LP, HS, HS/PLL and XT modes only) +
    2 ms (for HS/PLL mode only) + 1.5 μs (for EC mode only)

where T_{CY} is the instruction cycle time, T_{PWRT} is the Power-up Timer period and T_{OSC} is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.

  2: When ICPRT = 1, this specification also applies to ICV_{PP}.

  3: At 0°C-50°C.

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